

SWITCHING  
N-CHANNEL POWER MOS FET  
INDUSTRIAL USE

DESCRIPTION

This product is N-Channel MOS Field Effect Transistor designed for DC/DC converters and power management switch.

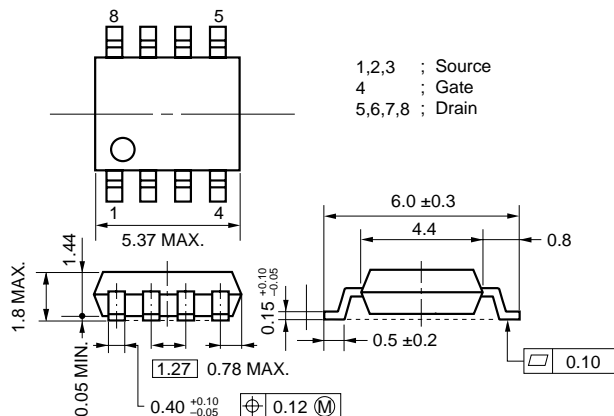
FEATURES

- Low on-resistance  
 $R_{DS(on)1} = 18.0 \text{ m}\Omega$  (TYP.) ( $V_{GS} = 10 \text{ V}$ ,  $I_D = 3.5 \text{ A}$ )  
 $R_{DS(on)2} = 28.0 \text{ m}\Omega$  (TYP.) ( $V_{GS} = 4.5 \text{ V}$ ,  $I_D = 3.5 \text{ A}$ )
- Low  $C_{iss}$  :  $C_{iss} = 730 \text{ pF}$  (TYP.)
- Built-in G-S protection diode
- Small and surface mount package (Power SOP8)

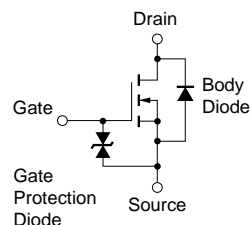
ORDERING INFORMATION

PART NUMBER	PACKAGE
$\mu$ PA1708G	Power SOP8

PACKAGE DRAWINGS (Unit : mm)



EQUIVALENT CIRCUIT



ABSOLUTE MAXIMUM RATINGS ( $T_A = 25^\circ\text{C}$ , All terminals are connected)

Drain to Source Voltage <sup>Note1</sup>	$V_{DSS}$	40	V
Gate to Source Voltage <sup>Note2</sup>	$V_{GSS}$	$\pm 25$	V
Drain Current (DC)	$I_{D(DC)}$	$\pm 7.0$	A
Drain Current (pulse) <sup>Note3</sup>	$I_{D(pulse)}$	$\pm 28$	A
Total Power Dissipation ( $T_A = 25^\circ\text{C}$ ) <sup>Note4</sup>	$P_T$	2.0	W
Channel Temperature	$T_{ch}$	150	$^\circ\text{C}$
Storage Temperature	$T_{stg}$	-55 to + 150	$^\circ\text{C}$

- Notes**
1.  $V_{GS} = 0 \text{ V}$
  2.  $V_{DS} = 0 \text{ V}$
  3.  $PW \leq 10 \mu\text{s}$ , Duty Cycle  $\leq 1 \%$
  4. Mounted on ceramic substrate of  $1200 \text{ mm}^2 \times 1.7 \text{ mm}$

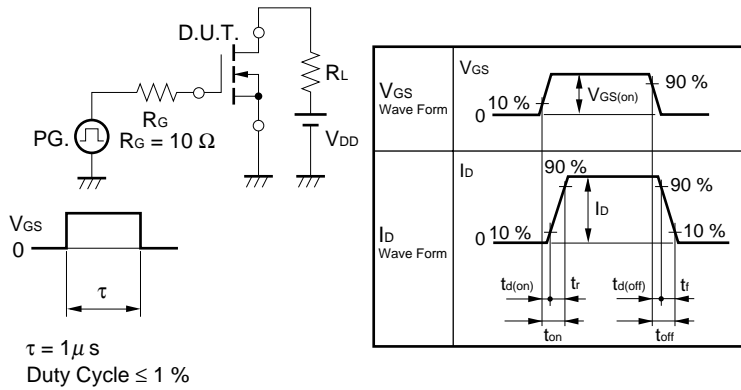
**Remark** The diode connected between the gate and source of the transistor serves as a protector against ESD. When this device actually used, an additional protection circuit is externally required if a voltage exceeding the rated voltage may be applied to this device.

The information in this document is subject to change without notice.

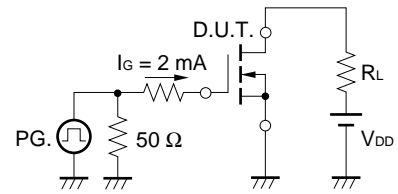
**ELECTRICAL CHARACTERISTICS (T<sub>A</sub> = 25°C, All terminals are connected)**

CHARACTERISTICS	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Drain to Source On-state Resistance	R <sub>DS(on)1</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 3.5 A		18.0	24.0	mΩ
	R <sub>DS(on)2</sub>	V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 3.5 A		28.0	40.0	mΩ
Gate to Source Cut-off Voltage	V <sub>GS(off)</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA	1.5	2.0	2.5	V
Forward Transfer Admittance	y <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 3.5 A	4.0	8.4		S
Drain Leakage Current	I <sub>DSS</sub>	V <sub>DS</sub> = 40 V, V <sub>GS</sub> = 0 V			10	μA
Gate to Source Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> = ±25 V, V <sub>DS</sub> = 0 V			±10	μA
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> = 10 V		730		pF
Output Capacitance	C <sub>oss</sub>	V <sub>GS</sub> = 0 V		340		pF
Reverse Transfer Capacitance	C <sub>rss</sub>	f = 1 MHz		150		pF
Turn-on Delay Time	t <sub>d(on)</sub>	I <sub>D</sub> = 3.5 A		16		ns
Rise Time	t <sub>r</sub>	V <sub>GS(on)</sub> = 10 V		96		ns
Turn-off Delay Time	t <sub>d(off)</sub>	V <sub>DD</sub> = 20 V		49		ns
Fall Time	t <sub>f</sub>	R <sub>G</sub> = 10 Ω		30		ns
Total Gate Charge	Q <sub>G</sub>	I <sub>D</sub> = 7.0 A		20		nC
Gate to Source Charge	Q <sub>GS</sub>	V <sub>DD</sub> = 32 V		2.5		nC
Gate to Drain Charge	Q <sub>GD</sub>	V <sub>GS</sub> = 10 V		6.8		nC
Body Diode Forward Voltage	V <sub>F(S-D)</sub>	I <sub>F</sub> = 7.0 A, V <sub>GS</sub> = 0 V		0.8		V
Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = 7.0 A, V <sub>GS</sub> = 0 V		32		ns
Reverse Recovery Charge	Q <sub>rr</sub>	di/dt = 100 A/ μs		25		nC

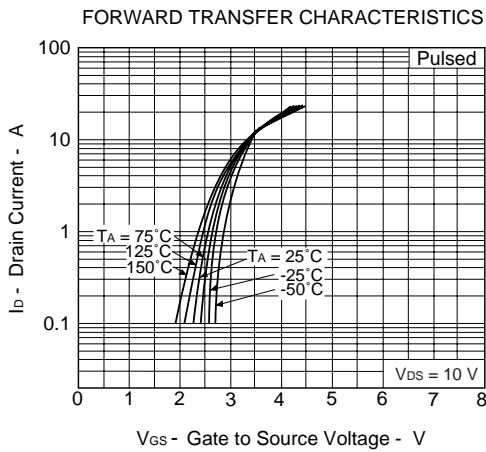
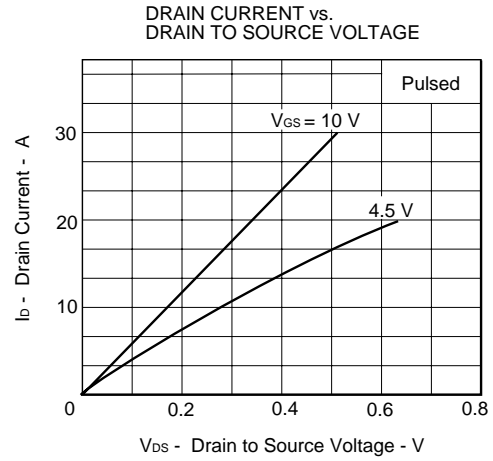
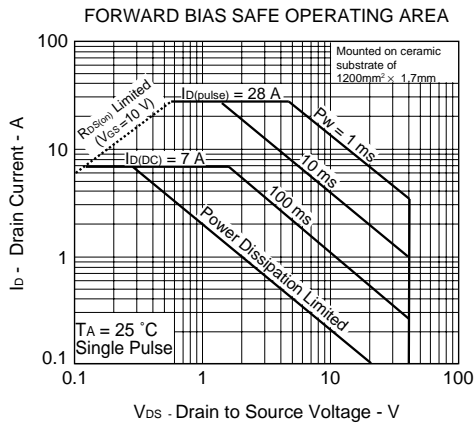
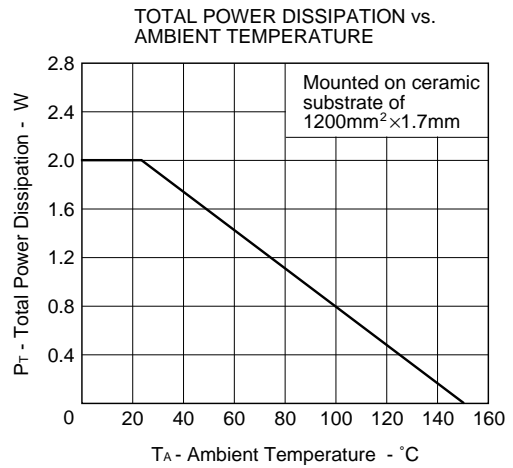
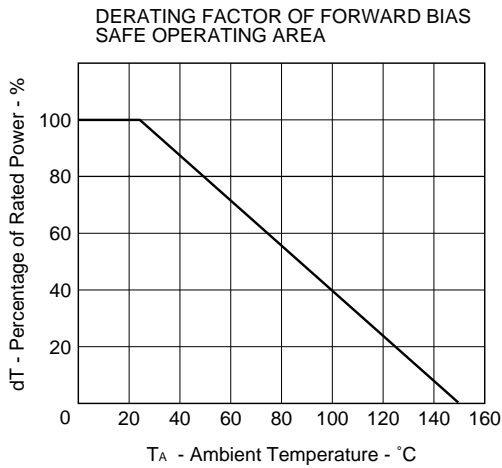
**TEST CIRCUIT 1 SWITCHING TIME**



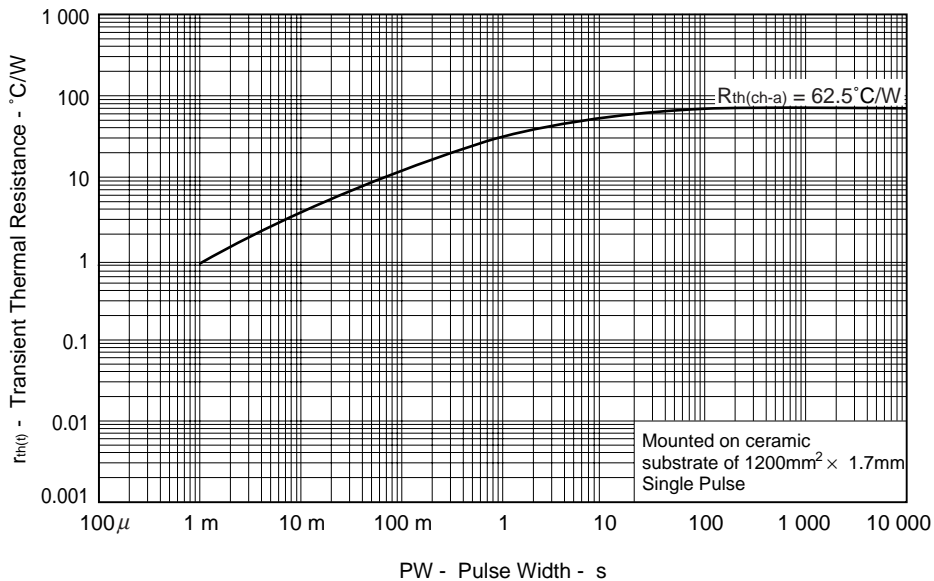
**TEST CIRCUIT 2 GATE CHARGE**



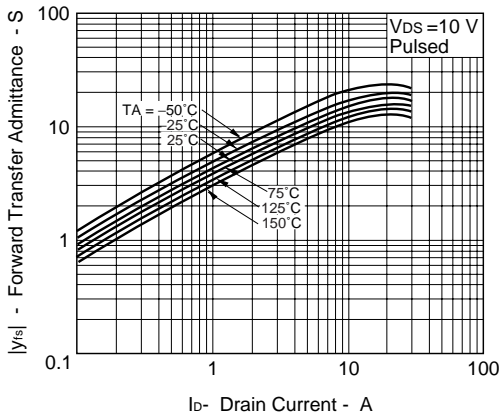
TYPICAL CHARACTERISTICS ( $T_A = 25^\circ\text{C}$ )



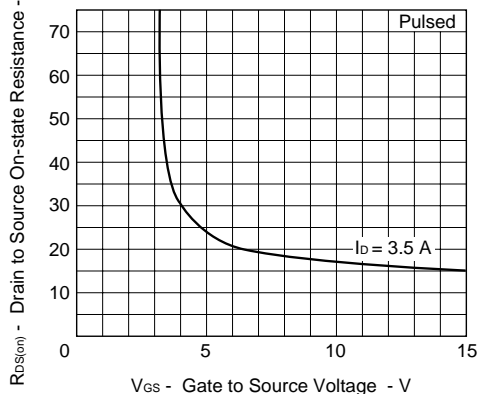
TRANSIENT THERMAL RESISTANCE vs. PULSE WIDTH



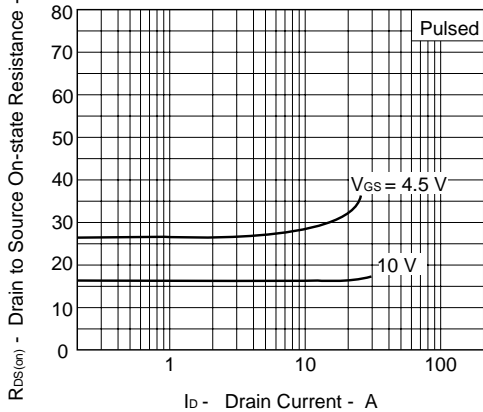
FORWARD TRANSFER ADMITTANCE vs. DRAIN CURRENT



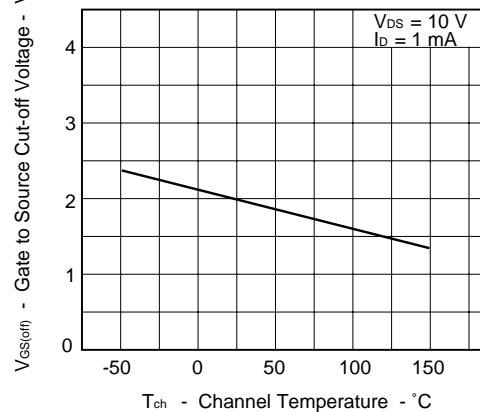
DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE

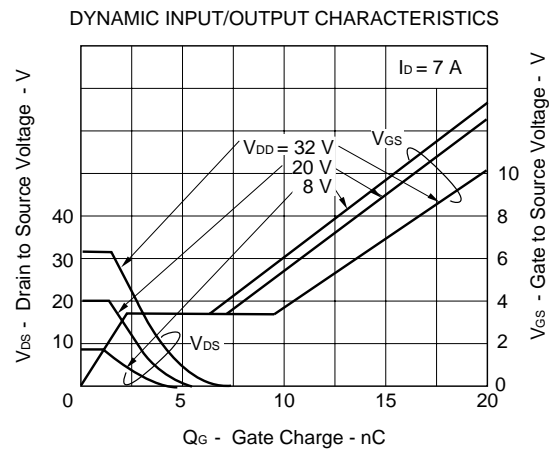
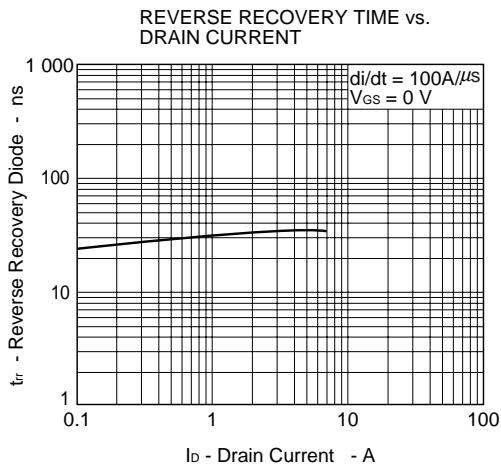
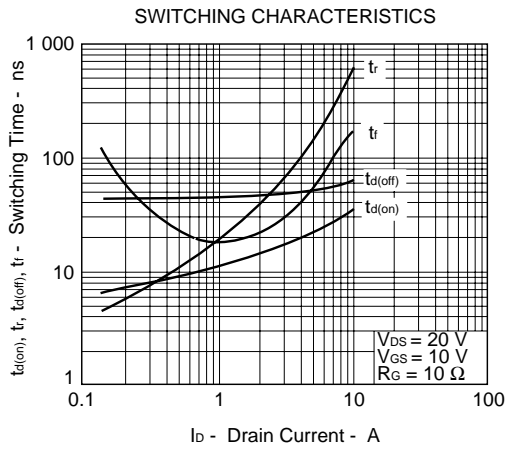
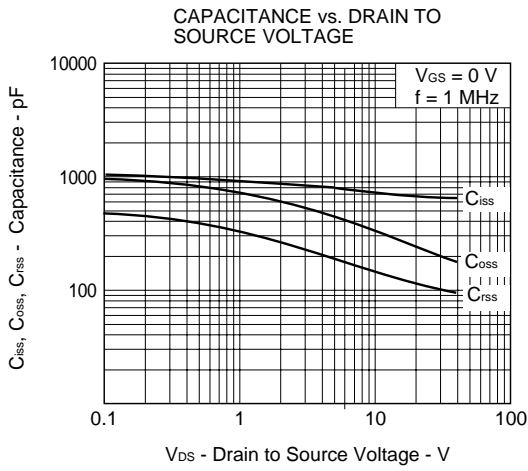
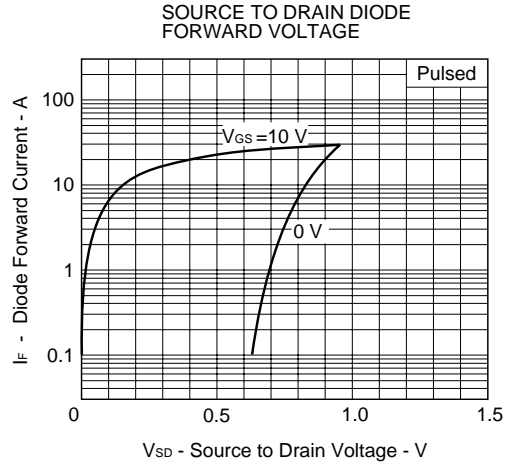
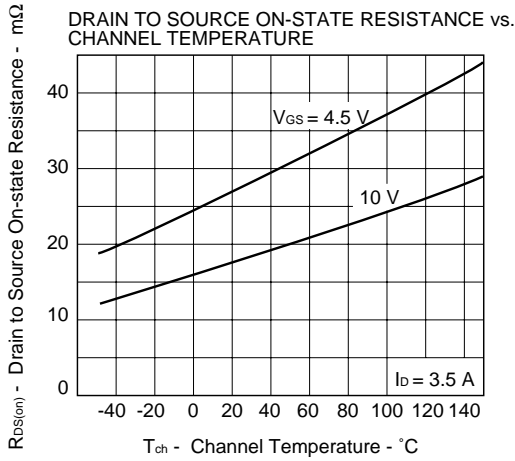


DRAIN TO SOURCE ON-STATE RESISTANCE vs. DRAIN CURRENT



GATE TO SOURCE CUT-OFF VOLTAGE vs. CHANNEL TEMPERATURE





[MEMO]

[MEMO]

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Anti-radioactive design is not implemented in this product.